

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
) Examiner: Not yet assigned
Madhav Datta et al.)
) Art Unit: Not yet assigned
Serial No.: Not yet assigned)
)
Filed: Herewith)
)
For: COPPER-CONTAINING C4 BALL-)
LIMITING METALLURGY STACK FOR ENHANCED)
RELIABILITY OF PACKAGED STRUCTURES)
AND METHOD OF MAKING SAME)
Which is a Divisional of Application of:)
)
Serial No: 09/961,034)
)
Filed: September 21, 2001)
Commissioner for Patents)
P.O. Box 1450)
Alexandria, Virginia 22313-1450)

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicant hereby requests consideration of the enclosed Information Disclosure Statement pursuant to 37 C.F.R. §1.97(b). Attached are the PTO Forms 1449 and Forms 892 from the parent application filed on September 21, 2001 (Serial No. 09/961,034). This previous application is relied upon for an earlier filing date under 35 U.S.C. §120.

Pursuant to C.F.R. §1.98(d), copies of the references are not being provided herewith since they were previously sent to the Patent and Trademark Office. Please consider these cited documents in the currently pending §1.53(b) parent application filed on September 21, 2001 (Serial No. 09/961,034).

FIRST CLASS CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on: February 10, 2004.
Date of Deposit

Teresa Mattox

Name of Person Mailing Correspondence

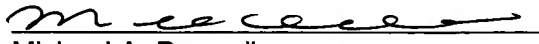
Teresa Mattox
SignatureFebruary 10, 2004
Date

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 2/10, 2004


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Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known

Applicant Number	09/961034
Filing Date	September 21, 2001
First Named Inventor	Datta, Madhav
Group Art Unit	2814
Examiner Name	Pham, Long

Sheet 1 of 1

Attorney Docket No: 884.522US1

US PATENT DOCUMENTS

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

Form 1449*	Atty. Docket No.: 884.522US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Madhav Datta et al.	
	Filing Date: Herewith	Group: Unknown

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**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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Examiner

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Notice of References Cited

Application/Control No.

09/961,034

Applicant(s)/Patent Under
Re examination
DATTA ET AL.

Examiner

Long Pham

Art Unit

2814

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	N					
	O					
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	S					
	T					

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*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.